

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Haruo Watanabe	06/03/2010
Tomoyo Ooyama	04/05/2010
Yosuke Hosoya	04/05/2010
Shigeru Fujita	04/05/2010

RECEIVING PARTY DATA

Name:	Sony Corporation
Street Address:	1-7-1 Konan, Minato-Ku
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12761172

CORRESPONDENCE DATA

Fax Number: (312)827-8185
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
 Phone: 312.807.4310
 Email: chicago.patents@klgates.com
 Correspondent Name: K&L Gates LLP
 Address Line 1: PO Box 1135
 Address Line 4: Chicago, ILLINOIS 60690-1135

ATTORNEY DOCKET NUMBER:	3712174-01946
NAME OF SUBMITTER:	Thomas C. Basso

Total Attachments: 4
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**PATENT
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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in POSITIVE ELECTRODE ACTIVE MATERIAL, METHOD FOR MANUFACTURING POSITIVE ELECTRODE ACTIVE MATERIAL AND NONAQUEOUS ELECTROLYTE BATTERY

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for applications for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues or any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto.

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces as follows: Serial Number: 12/761,172, Filing Date: April 15, 2010.

This assignment executed on the dates indicated below.

HARUO WATANABE	
Name of first or sole inventor	Execution date of U.S. Patent Application
KANAGAWA JAPAN	
Residence of first or sole inventor	
<i>Haruo Watanabe</i>	<i>June 3, 2010.</i>
Signature of first or sole inventor	Date of this assignment
TOMOYO OYAMA	
Name of second inventor	Execution date of U.S. Patent Application
FUKUSHIMA JAPAN	
Residence of second inventor	
Signature of second inventor	Date of this assignment

YOSUKE HOSOYA

Name of third inventor

Execution date of U.S. Patent Application

FUKUSHIMA JAPAN

Residence of third inventor

Signature of third inventor

Date of this assignment

SHIGERU FUJITA

Name of fourth inventor

Execution date of U.S. Patent Application

FUKUSHIMA JAPAN

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Name of fifth inventor

Execution date of U.S. Patent Application

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

Name of sixth inventor

Execution date of U.S. Patent Application

Residence of sixth inventor

Signature of sixth inventor

Date of this assignment

Name of seventh inventor

Execution date of U.S. Patent Application

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment

Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in **POSITIVE ELECTRODE ACTIVE MATERIAL, METHOD FOR MANUFACTURING POSITIVE ELECTRODE ACTIVE MATERIAL AND NONAQUEOUS ELECTROLYTE BATTERY** for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, **SONY CORPORATION**, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

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This assignment executed on the dates indicated below.

HARUO WATANABE
Name of first or sole inventor
KANAGAWA JAPAN
Residence of First or sole inventor

Execution date of U.S. Patent Application

Signature of first or sole inventor

Date of this assignment

TOMOYO OYAMA
Name of second inventor
FUKUSHIMA JAPAN
Residence of second inventor

Execution date of U.S. Patent Application

Tomoyo Oyama
Signature of second inventor

April 5, 2010
Date of this assignment

YOSUKE HOSOYA
Name of third inventor
FUKUSHIMA JAPAN
Residence of third inventor

Execution date of U.S. Patent Application

Yusuke Hosoya
Signature of third inventor

April 5, 2010
Date of this assignment

ADDITIONAL INVENTOR(S)

SHIGERU FUJITA

Name of fourth inventor

FUKUSHIMA JAPAN

Residence of fourth inventor

Shigeru Fujita

Signature of fourth inventor

Execution date of U.S. Patent Application

April 5, 2010 *April 5, 2010*
~~*April 10, 2010*~~ *S.F.*

Date of this assignment

Name of fifth inventor

Execution date of U.S. Patent Application

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

Name of sixth inventor

Execution date of U.S. Patent Application

Residence of sixth inventor

Signature of sixth inventor

Date of this assignment

Name of seventh inventor

Execution date of U.S. Patent Application

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment

Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment